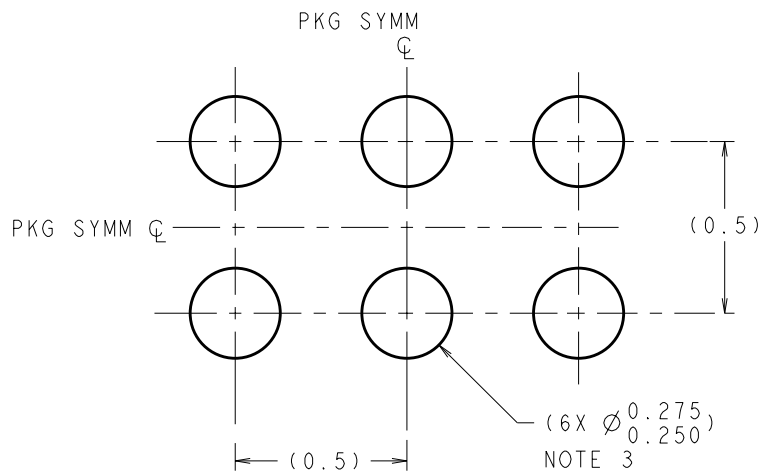
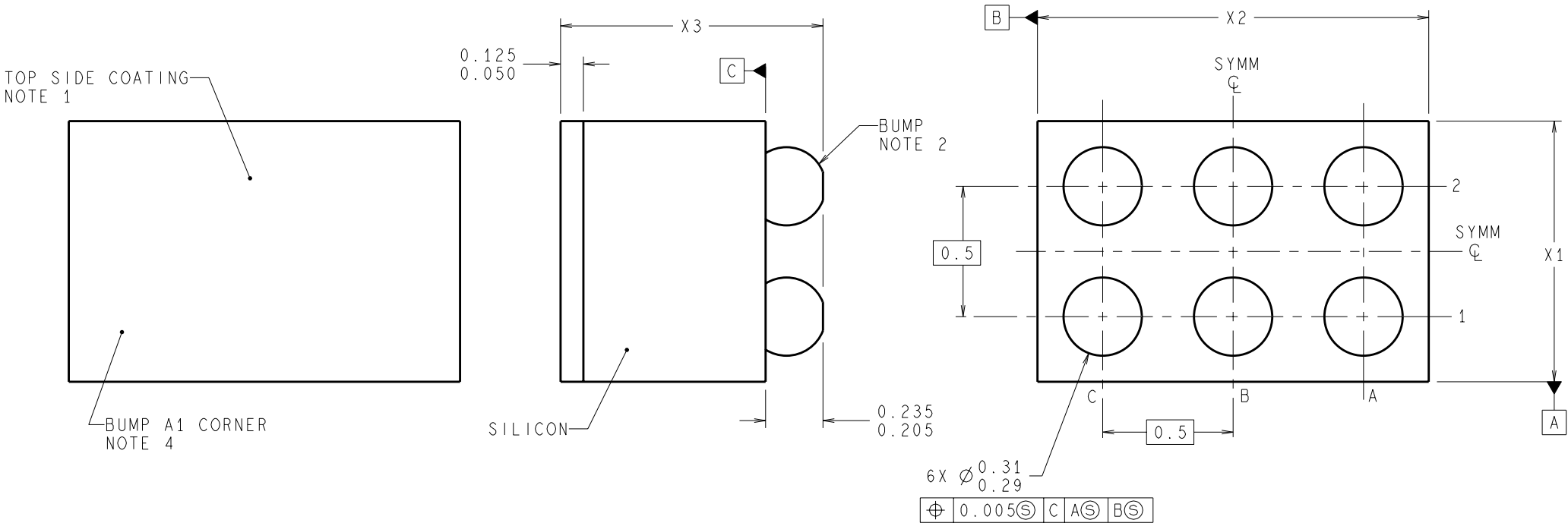


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	299	04/13/2001	MS/VP
B	CHANGE BUMPS NUMBERING ORDER PER JEDEC; JEDEC VARIATION WAS BC; UPDATE NOTE 4.	516	02/11/2002	MS/VP



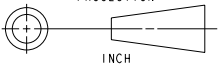
DIMENSIONS ARE IN MILLIMETERS

LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

1. EPOXY COATING.
2. 63Sn / 37Pb EUTECTIC BUMP.
3. RECOMMEND NON-SOLDER MASK DEFINED LANDING PAD.
4. PIN A1 IS ESTABLISHED BY LOWER LEFT CORNER WITH RESPECT TO TEXT ORIENTATION.
5. XXX IN DRAWING NUMBER REPRESENTS PACKAGE SIZE VARIATION WHERE X1 IS PACKAGE WIDTH, X2 IS PACKAGE LENGTH AND X3 IS PACKAGE HEIGHT (SEE TABLE, SHEET 2).
EXAMPLE: BLA06AFA HAS WIDTH=1006, LENGTH=1641, HEIGHT=795
6. REFERENCE JEDEC REGISTRATION MO-211, VARIATION BB.

APPROVALS		DATE		 <i>National Semiconductor</i> 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY		04/13/2001		
DFTG. CHK.	THANH LEQUANG		02/11/2002	MICRO SMD, 6 BUMP(LARGE), 0.5mm PITCH	
ENGR. CHK.	VIRAJ PATWARDHAN		02/11/2002		
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-BLA06XXX	B
DO NOT SCALE DRAWING				SHEET 1 of 2	

REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
	SEE SHEET 1			

PACKAGE DIMENSIONS					
X1 DESIGNATOR	X1 PACKAGE WIDTH ±30μm	X2 DESIGNATOR	X2 PACKAGE LENGTH ±30μm	X3 DESIGNATOR	X3 PACKAGE HEIGHT ±100μm
A	1006	A	1514	A	795
B	1031	B	1539	B	945
C	1057	C	1565	C	995
D	1082	D	1590		
E	1107	E	1615		
F	1133	F	1641		
G	1158	G	1666		
H	1184	H	1692		
J	1209	J	1717		
K	1234	K	1742		
L	1260	L	1768		
M	1285	M	1793		
N	1311	N	1819		
P	1336	P	1844		
Q	1361	Q	1869		
R	1387	R	1895		
S	1412	S	1920		
T	1438	T	1946		
U	1463	U	1971		

APPROVALS		DATE		National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	MARTA SUCHY	04/13/2001			
DFTG. CHK.	THANH LEQUANG	02/11/2002			
ENGR. CHK.	VIRAJ PATWARDHAN	02/11/2002			
PROJECTION  INCH [MM]		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-BLA06XXX	B
		DO NOT SCALE DRAWING		SHEET 2 of 2	